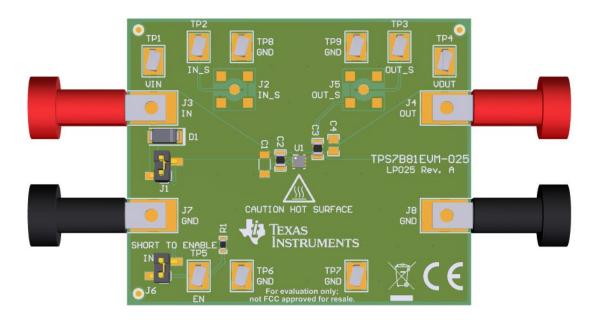


TPS7B81EVM-025 Evaluation module



This user's guide describes the operational use of the TPS7B81EVM-025 evaluation module (EVM) as a reference design for engineering demonstration and evaluation of the TPS7B8150QDRVRQ1 low-dropout linear regulator (LDO). Included in this user's guide are setup and operating instructions, thermal and layout guidelines, a printed circuit board (PCB) layout, a schematic diagram, and a bill of materials (BOM).

Throughout this document, the terms demonstration kit, evaluation board, and evaluation module are synonymous with the TPS7B81EVM-025.

Table 1 lists the related documentation available through the Texas Instruments web site at www.ti.com.

Table 1. Related Documentation

Device	Literature Number		
TPS7B81-Q1	SBVS370		



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www.ti.com Introduction

1 Introduction

Texas Instruments' TPS7B81EVM-025 EVM helps design engineers evaluate the operation and performance of the TPS7B81-Q1 family of linear regulators for possible use in their own circuit application. This particular EVM configuration contains a single 150-mA high-voltage, ultralow-IQ, low-dropout regulator for automotive systems. The regulator is capable of delivering up to 150 mA to the load with a wide V_{IN} range of up to 40 V (45 V transient). For stability, use a 2.2- μ F (or larger) output capacitor for the TPS7B81-Q1.

1.1 Before You Begin

The following warnings and cautions are noted for the safety of anyone using or working close to the TPS7B81EVM-025. Observe all safety precautions.



Warning

Warning hot surface. Contact may cause burns. Do not touch.

CAUTION

The circuit module may be damaged by overtemperature. To avoid damage, monitor the temperature during evaluation and provide cooling, as needed, for your system environment.

CAUTION

Some power supplies can be damaged by application of external voltages. If using more than one power supply, check your equipment requirements and use blocking diodes or other isolation techniques, as needed, to prevent damage to your equipment.

CAUTION

The circuit module is not a finished product or electrical appliance. The module does not contain current or voltage thresholds for circuit protection. This module must be used by qualified personnel with additional equipment for evaluation only.



EVM Setup www.ti.com

2 EVM Setup

This section describes how to properly connect and setup the TPS7B81EVM-025, including the jumpers and connectors on the EVM board.

2.1 Input/Output Connectors and Jumper Descriptions

2.1.1 J1 - DIODE BYPASS

Diode D1 bypass. To bypass diode D1, connect a jumper to short the two terminals of J1.

2.1.2 J2 - IN S

Input sense.

2.1.3 J3 - IN

Input power-supply voltage connector. Twist together the positive input lead and ground return lead from the input power supply, and keep them as short as possible to minimize input inductance.

2.1.4 J4 – OUT

Regulated output voltage connector.

2.1.5 J5 – OUT_S

Output sense.

2.1.6 J6 – SHORT TO ENABLE

Output enable. To enable the output, connect a jumper to short V_{IN} to EN.

There is a pulldown resistor, R1, between EN and GND so that the output is disabled when EN is not driven to a higher voltage. If making I_{GND} measurements, be sure to remove R1.

2.1.7 J7 – GND

Input ground return connector.

2.1.8 J8 – GND

Output ground return connector.

2.1.9 TP1 - VIN

V_{IN} test point.

2.1.10 TP2 - IN S

Input sense test point.

2.1.11 TP3 - OUT_S

Output sense test point.

2.1.12 TP4 - VOUT

V_{OUT} test point.

2.1.13 TP5 - EN

Enable test point.



www.ti.com EVM Setup

2.1.14 TP6 - GND

Ground test point.

2.1.15 TP7 - GND

Ground test point.

2.1.16 TP8 - GND

Ground test point.

2.1.17 TP9 - GND

Ground test point.

2.2 Soldering Guidelines

To avoid damaging the integrated circuit (IC), use a hot-air system for any solder rework to modify the EVM for the purpose of repair or other application reasons.

2.3 Equipment Connection

Connect the equipment as described in the following steps:

- 1. Set the input power supply up to 40 V (max), and turn the power supply off.
- 2. Connect the positive voltage lead from the input power supply to IN at the J3 connector of the EVM.
- 3. Connect the ground lead from the input power supply to GND at the J7 connector of the EVM.
- 4. Connect a 0-A to 150-mA load between OUT at the J4 and GND at the J8 connector of the EVM.
- 5. Disable the output by floating J6.

3 Operation

Operate the equipment using the following steps:

- 1. Turn on the power supplies.
- 2. Enable the output by jumping J6 (the EN pin) to VIN.
- 3. Vary the respective load and input voltage, as necessary, for test purposes.



PCB Layout www.ti.com

4 PCB Layout

Figure 1 to Figure 3 show the PCB layout for this EVM.

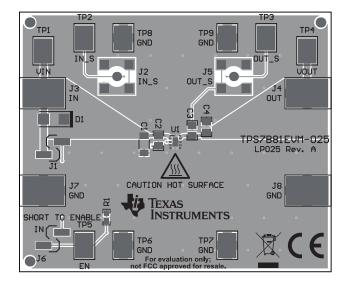


Figure 1. Assembly Layer

Figure 2. Top Layer Routing

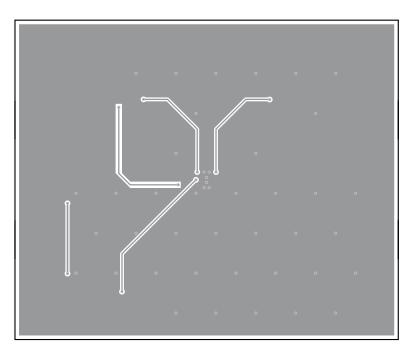


Figure 3. Bottom Layer Routing



www.ti.com Schematic

5 Schematic

Figure 4 is the schematic for this EVM.

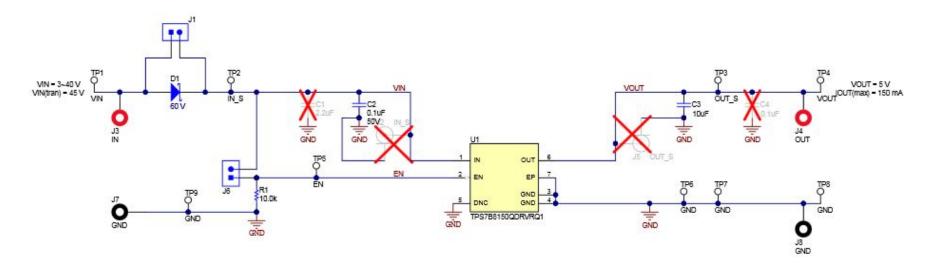


Figure 4. TPS7B81EVM-025 Schematic



Bill of Materials www.ti.com

6 Bill of Materials

Table 2 shows the BOM for this EVM.

Table 2. TPS7B81EVM-025 BOM(1)(2)(3)(4)

Designator	QTY	Value	Description	Package Reference	Part Number	Manufacturer	Alternate Part Number	Alternate Manufacture r
!PCB1	1		Printed Circuit Board		LP025	Any		
C2	1	0.1uF	CAP, CERM, 0.1 uF, 50 V, +/- 10%, X7R, AEC-Q200 Grade 1, 0805	0805	GCM21BR71H104KA37K	MuRata		
C3	1	10uF	CAP, CERM, 10 uF, 25 V, +/- 10%, X7R, 0805	0805	GRM21BZ71E106KE15L	MuRata	GRM21BC71E10 6ME11L	MuRata
D1	1	60V	Diode, Schottky, 60 V, 2 A, SMA	SMA	B260A-13-F	Diodes Inc.		
J1, J6	2		Header, 2.54 mm, 2x1, Gold, R/A, SMT	Header, 2.54 mm, 2x1, R/A, SMT	878980204	Molex		
J3, J4	2		Standard Banana Jack, Insulated, Red	6091	6091	Keystone		
J7, J8	2		Standard Banana Jack, Insulated, Black	6092	6092	Keystone		
R1	1	10.0k	RES, 10.0 k, 1%, 0.1 W, 0603	0603	RCG060310K0FKEA	Vishay Draloric		
SH-J1, SH-J2	2	1x2	Shunt, 100mil, Gold plated, Black	Shunt	SNT-100-BK-G	Samtec	969102-0000-DA	3M
TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9	9		Test Point, Compact, SMT	Testpoint_Keystone_Compact	5016	Keystone		
U1	1		150-mA High-Voltage Ultralow-IQ Low-Dropout Regulator, DRV0006A (WSON-6)	DRV0006A	TPS7B8150QDRVRQ1R	Texas Instruments	TPS7B8150QDR VRQ1T	Texas Instruments
C1	0	2.2uF	CAP, CERM, 2.2 uF, 50 V, +/- 10%, X7R, 1206	1206	GRM31CR71H225KA88L	MuRata		
C4	0	0.1uF	CAP, CERM, 0.1 uF, 50 V, +/- 10%, X7R, 0805	0805	GRM21BR71H104KA01L	MuRata		
FID1, FID2, FID3	0		Fiducial mark. There is nothing to buy or mount.	N/A	N/A	N/A		
J2, J5	0		Connector, SMA Jack, Vertical, Gold, SMD	SMA	142-0711-201	Cinch Connectivity		

⁽¹⁾ These assemblies are ESD sensitive, observe ESD precautions.

These assemblies must be clean and free from flux and all contaminants. Use of no-clean flux is not acceptable.

⁽³⁾ These assemblies must comply with workmanship standards IPC-A-610 Class 2.

⁽⁴⁾ Unless otherwise noted in the Alternate Part Number or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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